

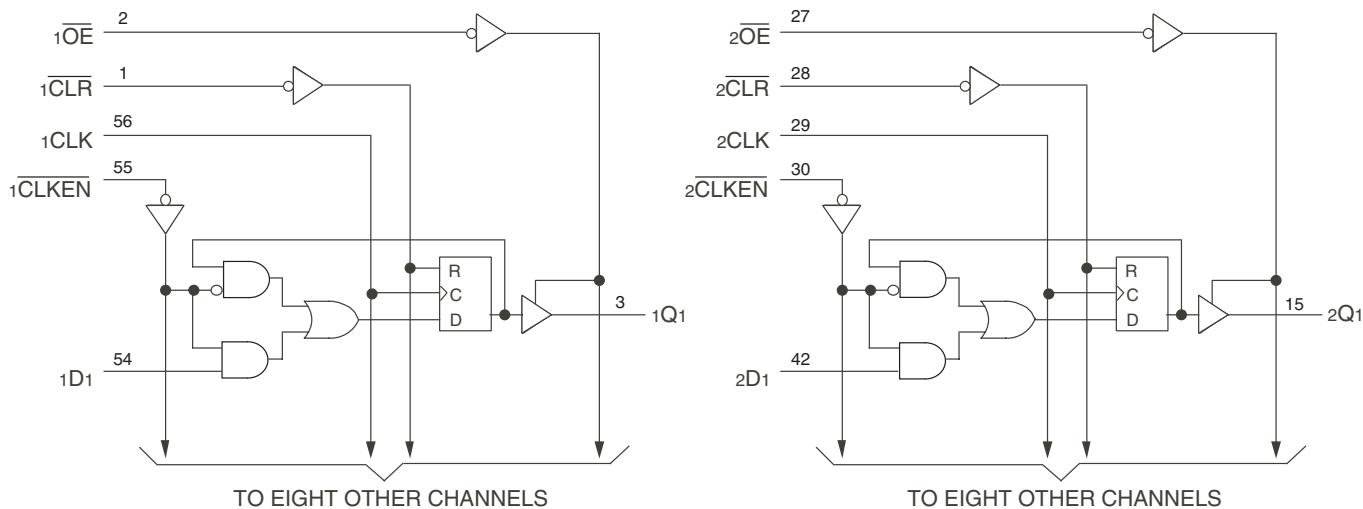
FEATURES:

- 0.5 MICRON CMOS Technology
- High-speed, low-power CMOS replacement for ABT functions
- Typical $t_{SK(O)}$ (Output Skew) < 250ps
- Low input and output leakage $\leq 1\mu\text{A}$ (max.)
- $V_{CC} = 5V \pm 10\%$
- Balanced Output Drivers of $\pm 24\text{mA}$
- Reduced system switching noise
- Typical VO_{LP} (Output Ground Bounce) < 0.6V at $V_{CC} = 5V$, $TA = 25^\circ\text{C}$
- Available in SSOP and TSSOP packages

DESCRIPTION:

The FCT162823T 18-bit bus interface register is built using advanced, dual metal CMOS technology. These high-speed, low-power registers with clock enable ($x\overline{CLKEN}$) and clear ($x\overline{CLR}$) controls are ideal for parity bus interfacing in high-performance synchronous systems. The control inputs are organized to operate the device as two 9-bit registers or one 18-bit register. Flow-through organization of signal pins simplifies layout. All inputs are designed with hysteresis for improved noise margin.

The FCT162823T has balanced output drive with current limiting resistors. This offers low ground bounce, minimal undershoot, and controlled output fall times – reducing the need for external series terminating resistors. The FCT162823T is a plug-in replacement for the FCT16823T and ABT16823 for on-board interface applications.

FUNCTIONAL BLOCK DIAGRAM

PIN CONFIGURATION

1 $\overline{\text{CLR}}$	1	56	1CLK
1 $\overline{\text{OE}}$	2	55	1 $\overline{\text{CLKEN}}$
1Q1	3	54	1D1
GND	4	53	GND
1Q2	5	52	1D2
1Q3	6	51	1D3
Vcc	7	50	Vcc
1Q4	8	49	1D4
1Q5	9	48	1D5
1Q6	10	47	1D6
GND	11	46	GND
1Q7	12	45	1D7
1Q8	13	44	1D8
1Q9	14	43	1D9
2Q1	15	42	2D1
2Q2	16	41	2D2
2Q3	17	40	2D3
GND	18	39	GND
2Q4	19	38	2D4
2Q5	20	37	2D5
2Q6	21	36	2D6
Vcc	22	35	Vcc
2Q7	23	34	2D7
2Q8	24	33	2D8
GND	25	32	GND
2Q9	26	31	2D9
2 $\overline{\text{OE}}$	27	30	2 $\overline{\text{CLKEN}}$
2 $\overline{\text{CLR}}$	28	29	2CLK

SSOP/ TSSOP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
V _{TERM} ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to 7	V
V _{TERM} ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to V _{cc} +0.5	V
T _{STG}	Storage Temperature	-65 to +150	°C
I _{OUT}	DC Output Current	-60 to +120	mA

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- All device terminals except FCT162XXX Output and I/O terminals.
- Outputs and I/O terminals for FCT162XXX.

CAPACITANCE (T_A = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	3.5	6	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	3.5	8	pF

NOTE:

- This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description
x _D x	Data Inputs
xCLK	Clock Inputs
x $\overline{\text{CLKEN}}$	Clock Enable Inputs (Active LOW)
x $\overline{\text{CLR}}$	Asynchronous clear Inputs (Active LOW)
x $\overline{\text{OE}}$	Output Enable Inputs (Active LOW)
xQx	3-State Outputs

FUNCTION TABLE⁽¹⁾

	Inputs					Outputs	Function
	x $\overline{\text{OE}}$	x $\overline{\text{CLR}}$	x $\overline{\text{CLKEN}}$	xCLK	x _D x		
H	X	X	X	X	X	Z	High Z
L	L	X	X	X	X	L	Clear
L	H	H	X	X	X	Q ⁽²⁾	Hold
H	H	L	L	↑	L	Z	Load
H	H	L	L	↑	H	Z	
L	H	L	L	↑	L	L	
L	H	L	L	↑	H	H	

NOTES:

- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
Z = High-Impedance
- Output level before indicated steady-state input conditions were established.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40°C to +85°C, VCC = 5.0V ±10%

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
VIH	Input HIGH Level	Guaranteed Logic HIGH Level		2	—	—	V
VIL	Input LOW Level	Guaranteed Logic LOW Level		—	—	0.8	V
I _{IH}	Input HIGH Current (Input pins) ⁽⁴⁾	VCC = Max.	VI = VCC	—	—	±1	µA
	Input HIGH Current (I/O pins) ⁽⁴⁾			—	—	±1	
I _{IL}	Input LOW Current (Input pins) ⁽⁴⁾		VI = GND	—	—	±1	
	Input LOW Current (I/O pins) ⁽⁴⁾			—	—	±1	
I _{OZH}	High Impedance Output Current	VCC = Max.	VO = 2.7V	—	—	±1	µA
I _{OZL}	(3-State Output pins) ⁽⁴⁾		VO = 0.5V	—	—	±1	
V _{IK}	Clamp Diode Voltage	VCC = Min., I _{IN} = -18mA		—	-0.7	-1.2	V
I _{OS}	Short Circuit Current	VCC = Max., VO = GND ⁽³⁾		-80	-140	-250	mA
V _H	Input Hysteresis	—		—	100	—	mV
I _{CCL}	Quiescent Power Supply Current	VCC = Max		—	5	500	µA
I _{CCH}		VIN = GND or VCC					
I _{CCZ}							

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
I _{ODL}	Output LOW Current	VCC = 5V, VIN = VIH or VIL, VO = 1.5V ⁽³⁾		60	115	200	mA
I _{ODH}	Output HIGH Current	VCC = 5V, VIN = VIH or VIL, VO = 1.5V ⁽³⁾		-60	-115	-200	mA
V _{OH}	Output HIGH Voltage	VCC = Min.	I _{OH} = -24mA	2.4	3.3	—	V
		VIN = VIH or VIL					
V _{OL}	Output LOW Voltage	VCC = Min.	I _{OL} = 24mA	—	0.3	0.55	V
		VIN = VIH or VIL					

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at VCC = 5.0V, +25°C ambient.
3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
4. This test limit for this parameter is ±5µA at TA = -55°C.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit	
ΔI_{CC}	Quiescent Power Supply Current TTL Inputs HIGH	V _{CC} = Max. V _{IN} = 3.4V ⁽³⁾		—	0.5	1.5	mA	
I _{CCD}	Dynamic Power Supply Current ⁽⁴⁾	V _{CC} = Max. Outputs Open $x\overline{OE} = x\overline{CLKEN} = GND$ One Input Toggling 50% Duty Cycle	V _{IN} = V _{CC} V _{IN} = GND	—	75	120	$\mu A/$ MHz	
I _C	Total Power Supply Current ⁽⁶⁾	V _{CC} = Max. Outputs Open f _{CP} = 10MHz 50% Duty Cycle $x\overline{OE} = x\overline{CLKEN} = GND$ at f _i = 5MHz 50% Duty Cycle One Bit Toggling	V _{IN} = V _{CC} V _{IN} = GND	—	0.8	1.7	mA	
		V _{CC} = Max. Outputs Open f _{CP} = 10MHz 50% Duty Cycle $x\overline{OE} = x\overline{CLKEN} = GND$ at f _i = 2.5MHz 50% Duty Cycle Eighteen Bits Toggling	V _{IN} = 3.4V V _{IN} = GND	—	1.3	3.2		
			V _{IN} = V _{CC} V _{IN} = GND	—	4.2	7.1 ⁽⁵⁾		
			V _{IN} = 3.4V V _{IN} = GND	—	9.2	22.1 ⁽⁵⁾		

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at V_{CC} = 5.0V, +25°C ambient.

3. Per TTL driven input (V_{IN} = 3.4V). All other inputs at V_{CC} or GND.

4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.

5. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.

6. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$

$$I_C = I_{CC} + \Delta I_{CC} D_{HNT} + I_{CCD} (f_{CP} N_{CP}/2 + f_i N_i)$$

I_{CC} = Quiescent Current (I_{CC1}, I_{CC2} and I_{CC3})

ΔI_{CC} = Power Supply Current for a TTL High Input (V_{IN} = 3.4V)

D_H = Duty Cycle for TTL Inputs High

N_T = Number of TTL Inputs at D_H

I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

f_{CP} = Clock Frequency for Register Devices (Zero for Non-Register Devices)

N_{CP} = Number of Clock Inputs at f_{CP}

f_i = Input Frequency

N_i = Number of Inputs at f_i

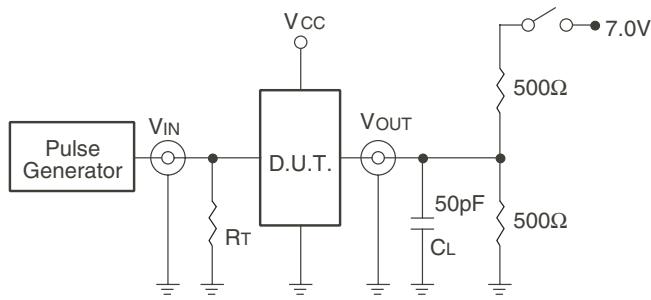
SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Symbol	Parameter	Condition ⁽¹⁾	FCT162823AT		FCT162823CT		Unit
			Min. ⁽²⁾	Max.	Min. ⁽²⁾	Max.	
t _{PLH} t _{PHL}	Propagation Delay xCLK _x to xO _x	CL = 50pF RL = 500Ω	1.5	10	1.5	4.7	ns
		CL = 300pF ⁽⁴⁾ RL = 500Ω	1.5	20	1.5	8	
t _{PHL}	Propagation Delay xCLR to xO _x	CL = 50pF RL = 500Ω	1.5	14	1.5	4.7	ns
t _{PZH} t _{PZL}	Output Enable Time xOE to xO _x	CL = 50pF RL = 500Ω	1.5	12	1.5	4.4	ns
		CL = 300pF ⁽⁴⁾ RL = 500Ω	1.5	23	1.5	9	
t _{PHZ} t _{PLZ}	Output Disable Time xOE to xO _x	CL = 50pF ⁽⁴⁾ RL = 500Ω	1.5	7	1.5	3.6	ns
		CL = 50pF RL = 500Ω	1.5	8	1.5	3.6	
tsu	Set-up Time HIGH or LOW xD _x to xCLK	CL = 50pF RL = 500Ω	3	—	1.5	—	ns
t _H	Hold Time HIGH or LOW, xD _x to xCLK		1.5	—	0	—	ns
tsu	Set-up Time HIGH or LOW, xCLKEN to xCLK		3	—	2.5	—	ns
t _H	Hold Time HIGH or LOW, xCLKEN to xCLK		0	—	0	—	ns
t _w	xCLK Pulse Width HIGH or LOW		6	—	3	—	ns
t _w	xCLR Pulse Width LOW		6	—	3	—	ns
t _{REM}	Recovery Time, xCLR to xCLK		6	—	3	—	ns
t _{SK(0)}	Output Skew ⁽³⁾		—	0.5	—	0.5	ns

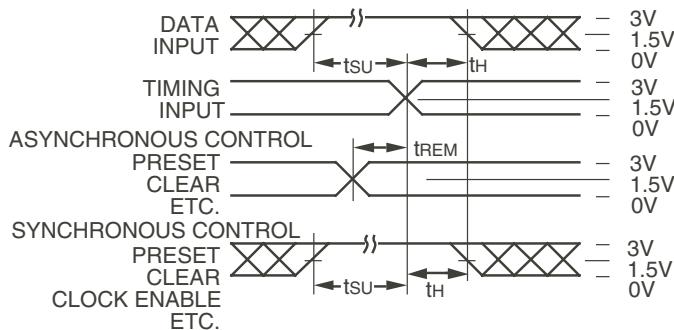
NOTES:

1. See test circuit and waveforms.
2. Minimum limits are guaranteed but not tested on Propagation Delays.
3. Skew between any two outputs, of the same package, switching in the same direction. This parameter is guaranteed by design.
4. This condition is guaranteed but not tested.

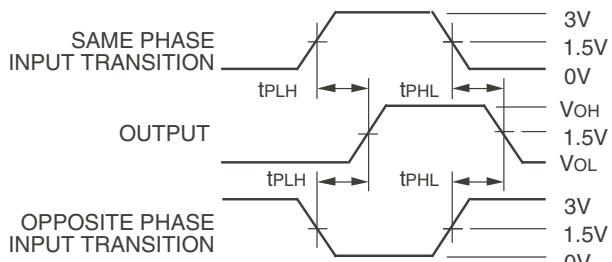
TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs



Set-up, Hold, and Release Times



Propagation Delay

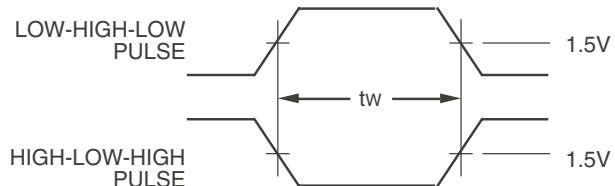
SWITCH POSITION

Test	Switch
Open Drain	Closed
Disable Low	
Enable Low	
All Other Tests	Open

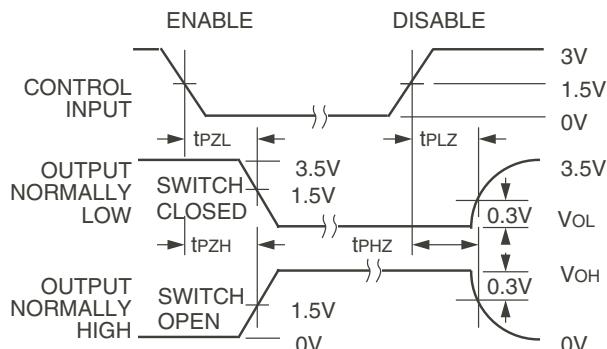
DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.

R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.



Pulse Width

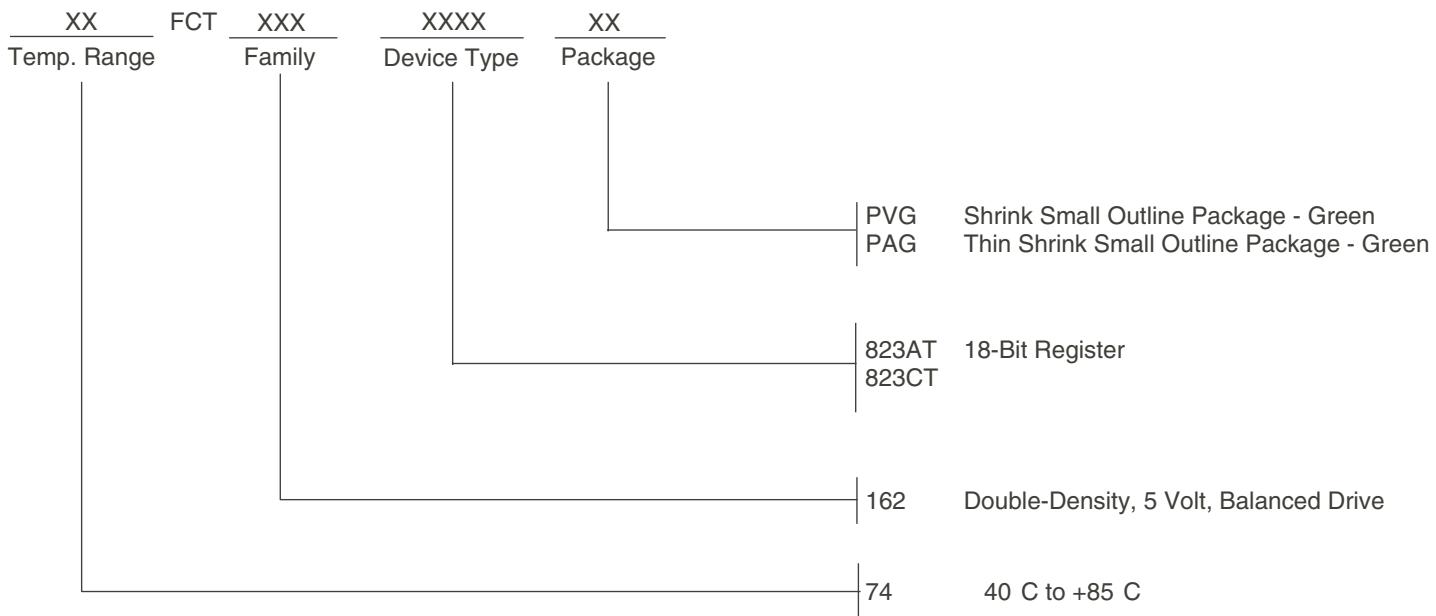


Enable and Disable Times

NOTES:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
2. Pulse Generator for All Pulses: Rate $\leq 1.0\text{MHz}$; $t_f \leq 2.5\text{ns}$; $t_r \leq 2.5\text{ns}$.

ORDERING INFORMATION



Datasheet Document History

09/06/09 Pg. 7 Updated the ordering information by removing the "IDT" notation and non RoHS part.

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